Zytel® HTN54G35EF BK420

HIGH PERFORMANCE POLYAMIDE RESIN

Zytel® HTN high performance polyamide resins feature high retention of properties upon exposure to elevated temperature, to high moisture, and to harsh chemical environments. Polymer families and grades of Zytel® HTN are tailored to optimize performance as well as processability.

Typical applications with Zytel® HTN include demanding applications in the automotive, electrical and electronics, domestic appliances, and construction industries.

Zytel® HTN54G35EF BK420 is a 35% glass reinforced, toughened, heat stabilized high performance polyamide resin, developed for electrical and electronics applications. It is also a PPA resin.

Product information

Resin Identification	PA-I-GF35	ISO 1043
Part Marking Code	>PA-I-GF35<	ISO 11469
Part Marking Code	>PPA-I-GF35<	SAE J1344
ISO designation	ISO 16396-PA-I,GF35,M1CGHR,S12-110	
TGA curve	available	ISO 11358-1

Rheological properties

	dry/cond.		
Viscosity number	3320 / *	in³/lb	ISO 307, 1628
Molding shrinkage, parallel	0.2 / -	%	ISO 294-4, 2577
Molding shrinkage, normal	0.5 / -	%	ISO 294-4, 2577

Typical mechanical properties

	dry/cond.		
Tensile modulus	1.6E6 / -	psi	ISO 527-1/-2
Tensile stress at break, 5mm/min	27600 / -	psi	ISO 527-1/-2
Tensile strain at break, 5mm/min	3 / -	%	ISO 527-1/-2
Flexural modulus	1.45E6 / -	psi	ISO 178
Flexural strength	39200 / -	psi	ISO 178
Charpy impact strength, 23°C	39 / -	ftlb/in²	ISO 179/1eU
Charpy notched impact strength, 23°C	5.23 / -	ftlb/in²	ISO 179/1eA

Thermal properties

	dry/cond.		
Melting temperature, 10°C/min	579 / *	°F	ISO 11357-1/-3
Glass transition temperature, 10°C/min	239 / 149	°F	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa	504 / *	°F	ISO 75-1/-2
Coefficient of linear thermal expansion (CLTE), parallel	0.11 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel, -40-23°C	0.111 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), parallel, 55-160°C	0.106 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal	0.333 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal, -40-23°C	0.306 / *	E-4/°F	ISO 11359-1/-2
Coefficient of linear thermal expansion (CLTE), normal, 55-160°C	0.6 / *	E-4/°F	ISO 11359-1/-2

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Flammability

	dry/cond.		
Oxygen index	23 / *	%	ISO 4589-1/-2
Glow Wire Flammability Index, 3.0mm	1760 / -	°F	IEC 60695-2-12
Glow Wire Ignition Temperature, 3.0mm	1470 / -	°F	IEC 60695-2-13
FMVSS Class	SE		ISO 3795 (FMVSS 302)

Electrical properties

	dry/cond.		
Relative permittivity, 100Hz	4.3 / -		IEC 62631-2-1
Relative permittivity, 1MHz	3.9 / -		IEC 62631-2-1
Dissipation factor, 100Hz	50 / -	E-4	IEC 62631-2-1
Dissipation factor, 1MHz	155 / -	E-4	IEC 62631-2-1
Volume resistivity	>1E13 / -	Ohm.m	IEC 62631-3-1
Electric strength	813 / 787	kV/in	IEC 60243-1
Comparative tracking index	600 / -		IEC 60112

Physical/Other properties

	dry/cond.		
Humidity absorption, 2mm	1.8 / *	%	Sim. to ISO 62
Density	0.0513 / -	lb/in³	ISO 1183

Injection

Drying Recommended	yes	
Drying Temperature	212	°F
Drying Time, Dehumidified Dryer	6 - 8	h
Processing Moisture Content	≤0.1	%
Melt Temperature Optimum	617	°F
Min. melt temperature	608	°F
Max. melt temperature	626	°F
Mold Temperature Optimum	230	°F
Min. mold temperature	185	°F
Max. mold temperature	275	°F
Hold Pressure Time (h is the max. wall thickness of the part in mm)	h^2+2	s
Ejection temperature	502	°F

Automotive

OEM	STANDARD	ADDITIONAL INFORMATION
Renault-Nissan	UB23, No Spec, Special Part Approval, See Your CE Account Manager.	
Stellantis	B62 / 0300 / 61/223E-217M	01378_19_02659

Characteristics

Processing	Injection Molding
Special characteristics	Heat stabilized or stable to heat

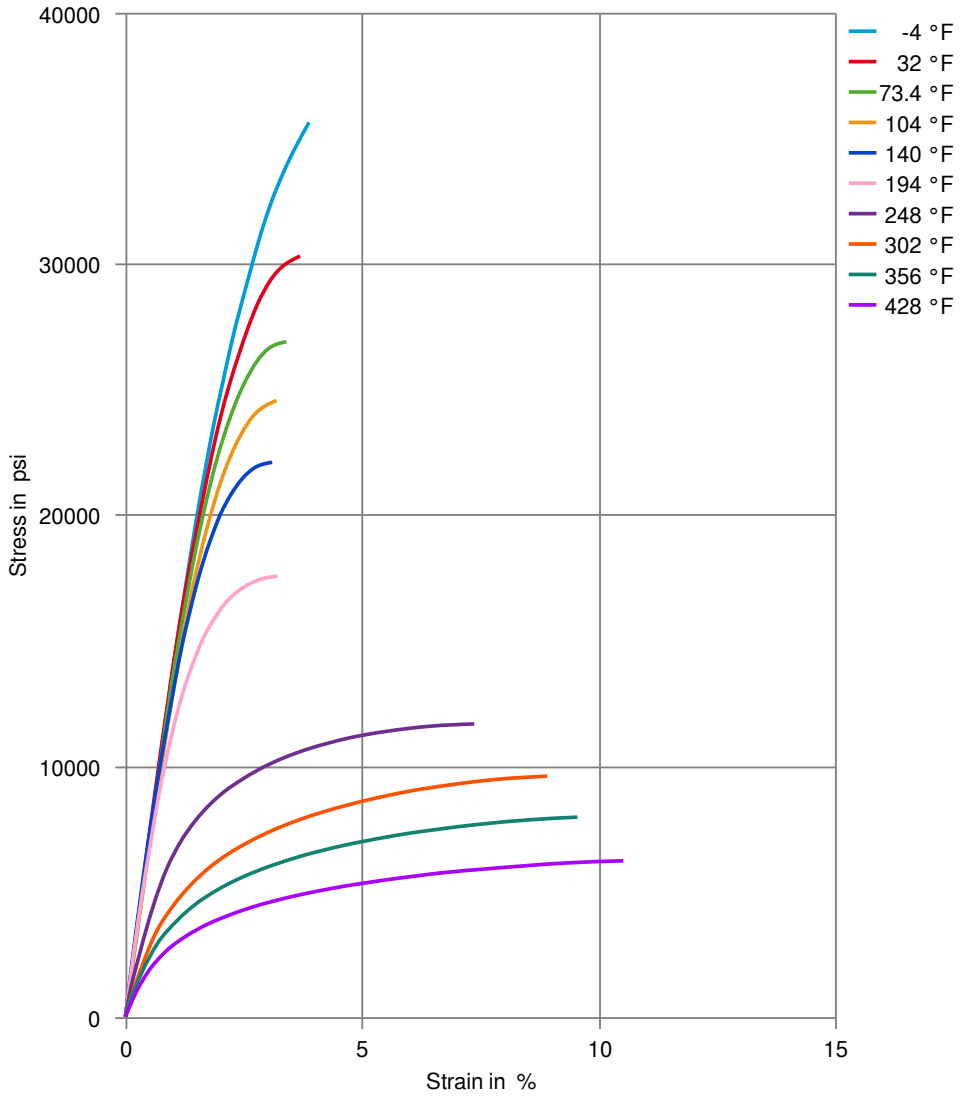
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Additional information

Injection molding	During molding, use proper protective equipment and adequate ventilation. Avoid exposure to fumes and limit the hold up time and temperature of the resin in the machine. Purge degraded resin carefully with HDPE.

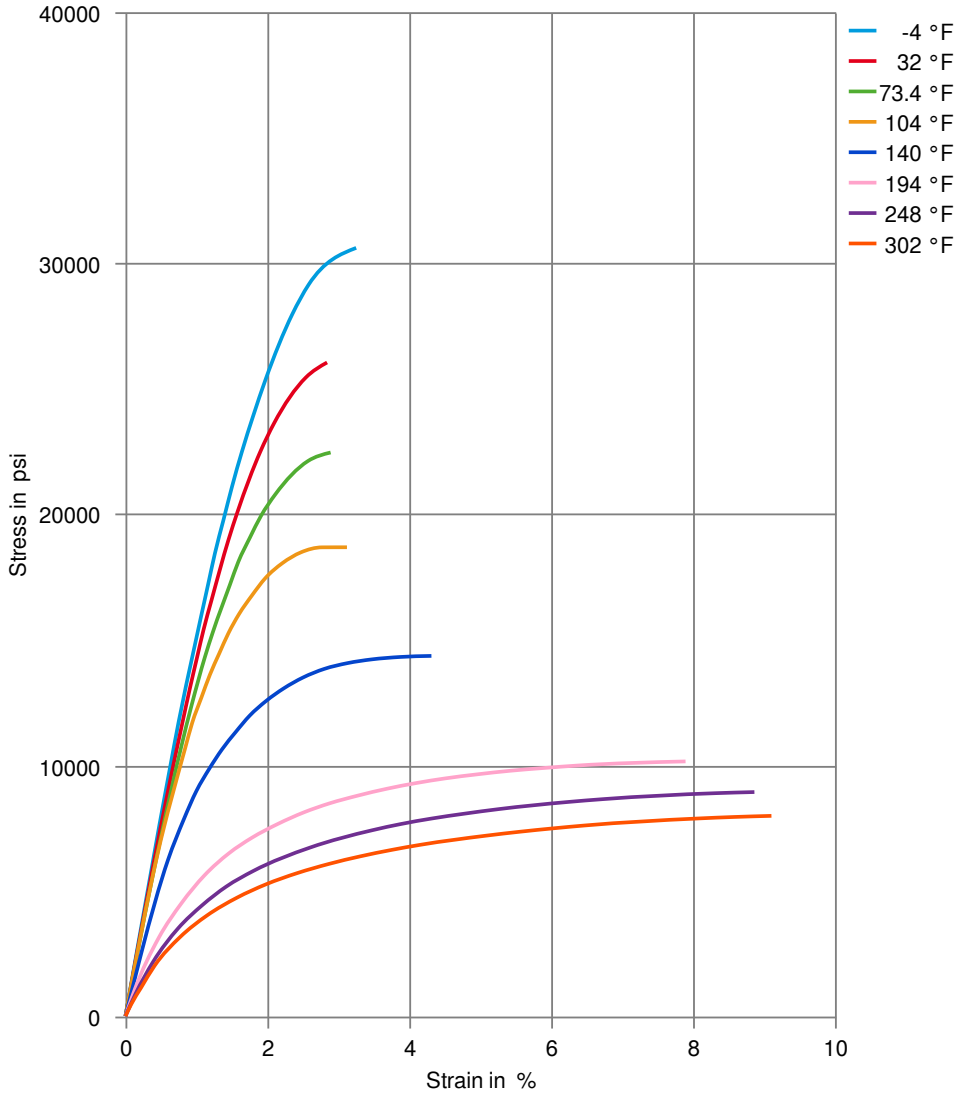
Stress-strain (dry)



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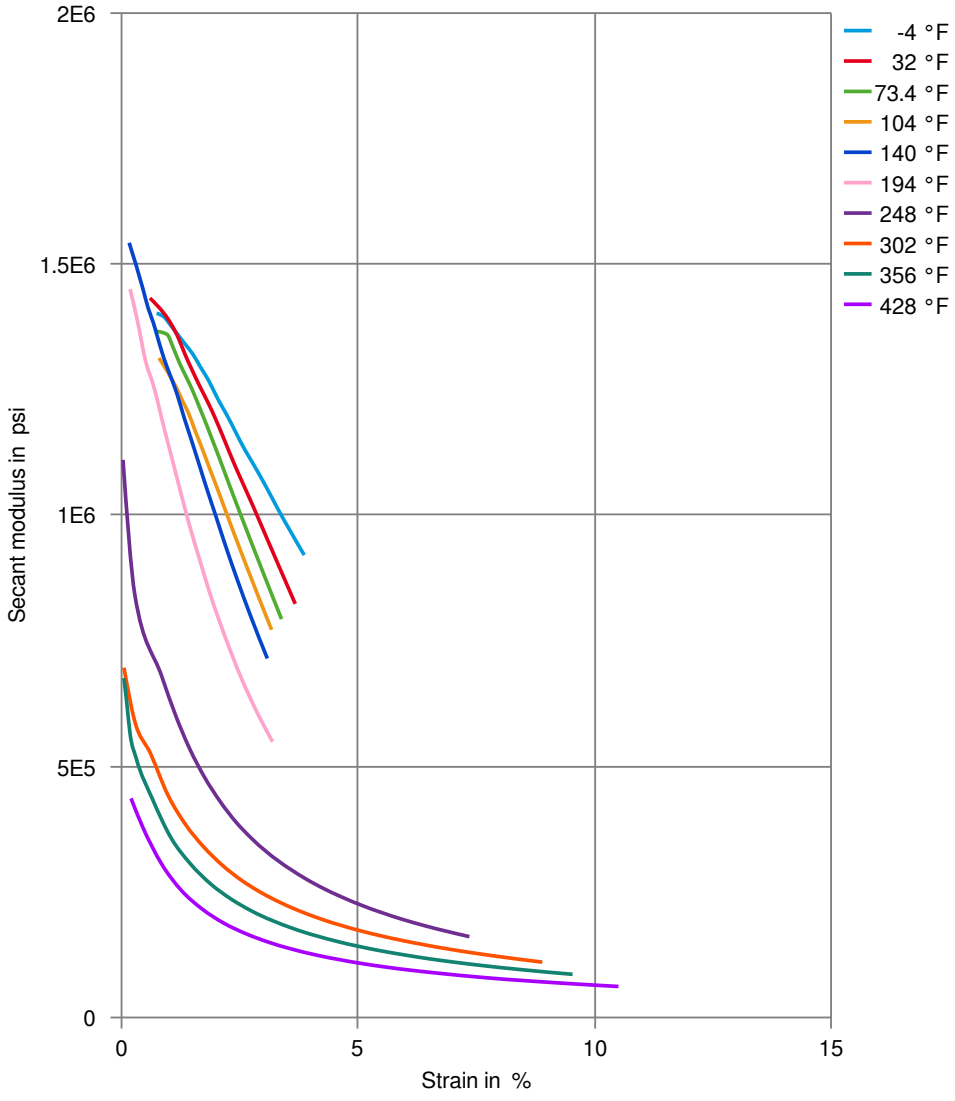
Stress-strain (cond.)



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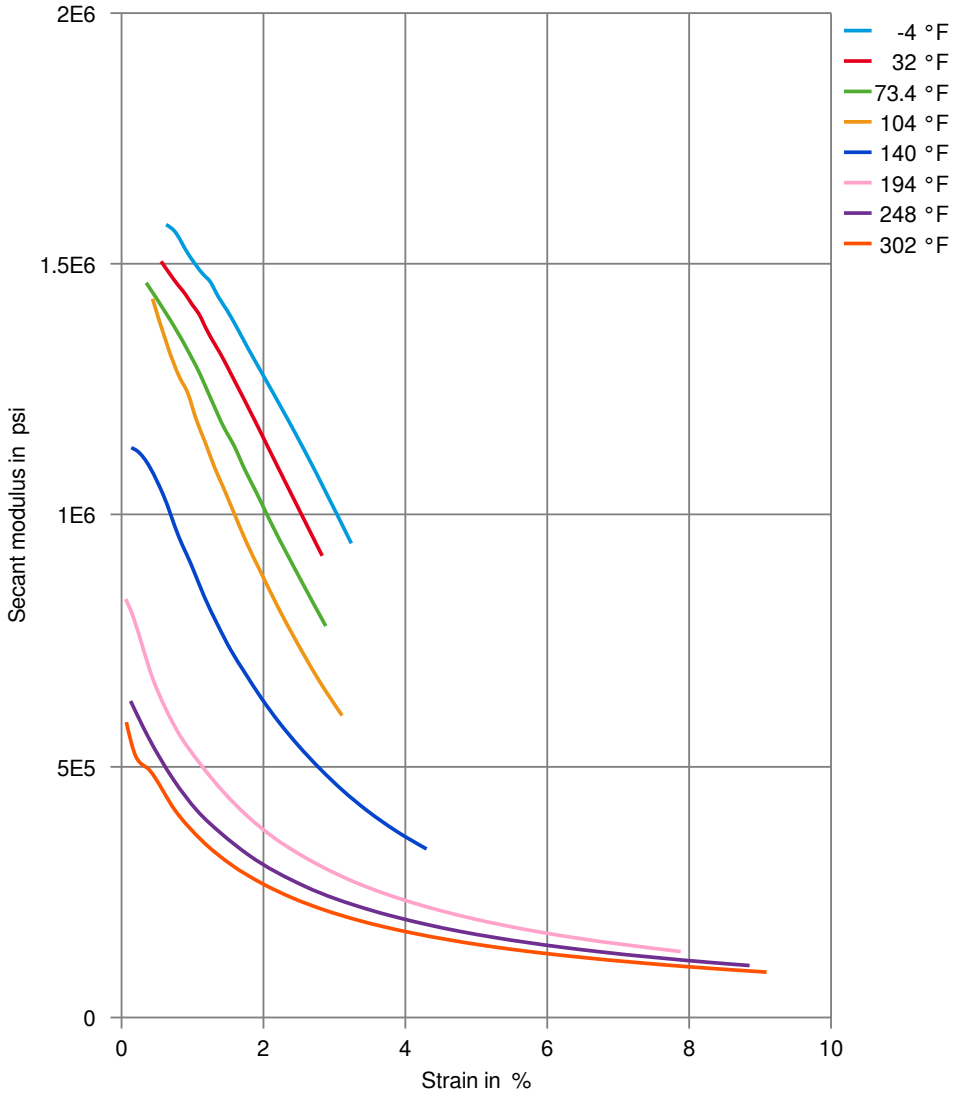
Secant modulus-strain (dry)



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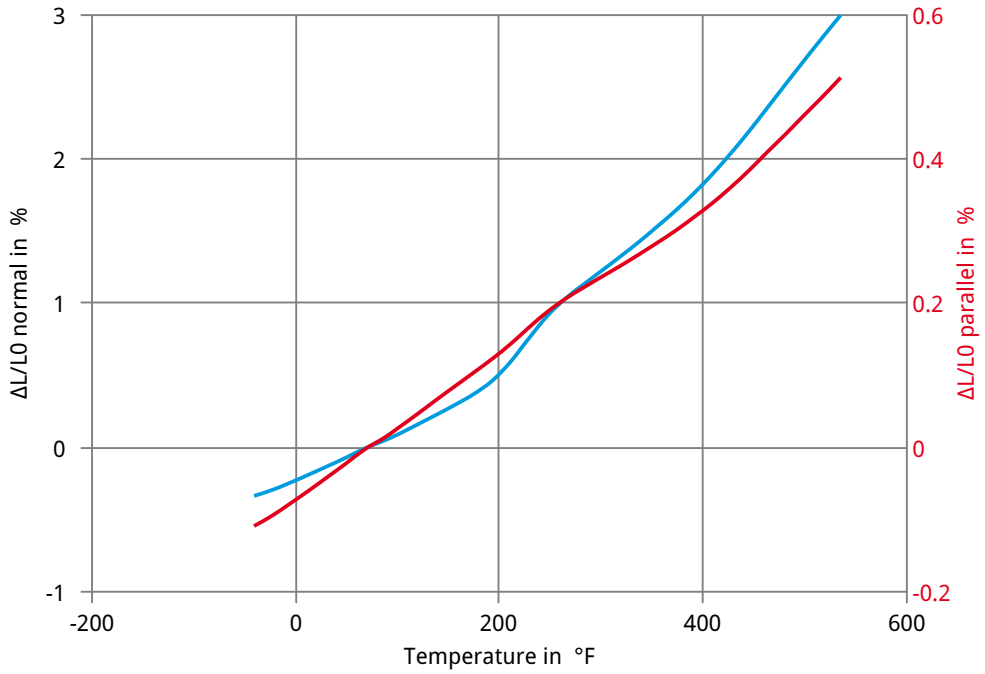
Secant modulus-strain (cond.)



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Thermal expansion



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Chemical Media Resistance

Other

- ✔ Urea solution (32.5% by mass), 23 °C

Symbols used:

- ✔ possibly resistant
  Defined as: Supplier has sufficient indication that contact with chemical can be potentially accepted under the intended use conditions and expected service life. Criteria for assessment have to be indicated (e.g. surface aspect, volume change, property change).
- ✘ not recommended - see explanation
  Defined as: Not recommended for general use. However, short-term exposure under certain restricted conditions could be acceptable (e.g. fast cleaning with thorough rinsing, spills, wiping, vapor exposure).

Revised: 2026-08-12 Source: Celanese Materials Database

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